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4/28/05  
05-04-2005



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To the Director of the U.S. Patent and T

Please record the attached documents or the new address(es) below.

**1. Name of conveying party(ies)/Execution Date(s):**

Kum-Weng Loo

Chek-Lim Kho

Execution Date(s) 12/03/2004, 12/03/2004

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

**3. Nature of conveyance:**

☒ Assignment

☐ Merger

☐ Security Agreement

☐ Change of Name

☐ Government Interest Assignment

☐ Executive Order 9424, Confirmatory License

☐ Other

**2. Name and address of receiving party(ies)**

Name: STMicroelectronics Asia Pacific Pte., Ltd.

Internal Address:

Street Address: 5A Serangoon North Avenue 5

Singapore 554574

City:

State:

Country:

Zip:

Additional name(s) & address(es) attached? ☐ Yes ☒ No

**4. Application or patent number(s):**

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

11/000,355

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

**5. Name and address to whom correspondence concerning document should be mailed:**

Name: Docket Clerk

Internal Address:

Street Address: P.O. Box 802432

City: Dallas

State: Texas Zip: 75380

Phone Number: 972-628-3600

Fax Number: 972-628-3616

Email Address:

**6. Total number of applications and patents involved:**

1

**7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00**

☐ Authorized to be charged by credit card

☐ Authorized to be charged to deposit account

☒ Enclosed

☐ None required (government interest not affecting title)

**8. Payment Information**

a. Credit Card Last 4 Numbers  
Expiration Date

b. Deposit Account Number 50-0208

Authorized User Name William A. Munck

**9. Signature:**

Signature

Date

William A. Munck, Reg. No. 39,308

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents:

3

Documents to be recorded (including cover sheet) should be faxed to (703) 306-5995, or mailed to:  
Mail Stop Assignment Recordation Services, Director of the USPTO, P.O. Box 1450, Alexandria, V.A. 22313-1450

05/03/2005 ECOOPER 00000167 11000355

01 FC:0021

40.00 DP

PATENT  
REEL: 016508 FRAME: 0101

**ASSIGNMENT**

WHEREAS, We, Kum-Weng Loo, a resident of Singapore, and citizen of Singapore, and Chek-Lim Kho, a resident of Singapore, and a citizen of Singapore, have invented certain new and useful improvements in "SIMPLIFIED MULTICHIP PACKAGING AND PACKAGE DESIGN" disclosed in an application for United States Letters Patent filed in the United States Patent and Trademark Office on November 30, 2004, and assigned Application Serial No. 11/000,355;

WHEREAS, STMICROELECTRONICS ASIA PACIFIC PTE., LTD., a corporation organized under the laws of Singapore, having a place of business at 5A Serangoon North Avenue 5, Singapore 554574 (hereinafter referred to as "ASSIGNEE"), is desirous of acquiring our entire right, title and interest in and to the invention, and in and to the said application and any Letters Patent that may issue thereon;

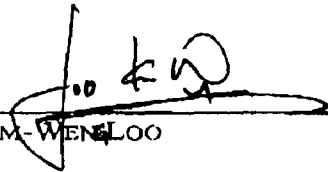
NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, we do hereby sell, assign and transfer unto said ASSIGNEE, its successors, assigns and legal representatives, the full and exclusive right, title and interest in and to said invention and in and to said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, continuations-in-part and extensions thereof; we authorize Lisa K. Jorgenson of STMicroelectronics, Inc. and William A. Munck, John T. Mockler Scott B. Stahl, and Daniel E. Venglarik of Davis Munck, P.C. to insert in the parenthesis above the application number and filing date of said application when known; and we hereby authorize and request the Commissioner of Patents and Trademarks to issue all patents for said invention, or patents resulting therefrom, insofar as our interest is concerned, to the said ASSIGNEE of our entire right, title and interest.

We also hereby sell and assign to said ASSIGNEE, its successors, assigns and legal representatives the full and exclusive rights, title and interest to the invention disclosed in said application throughout the world, including the right to file applications and obtain patents, utility models, industrial models and designs for said invention in its own name throughout the world including all rights of priority, all rights to publish cautionary notices reserving ownership of said invention and all rights to register said invention in appropriate registries; and we further agree to execute any and all powers of attorney, applications, assignments, declarations, affidavits, and any other papers in connection therewith necessary to perfect such rights, title and interest in ASSIGNEE, its successors, assigns and legal representatives.

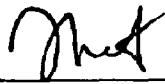
We hereby further agree that we will communicate to said ASSIGNEE, or to its successors, assigns and legal representatives, any facts known to us respecting any improvements; and, at the expense of said ASSIGNEE, to testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, continuation-in-part, reissue and substitute applications, and make all lawful

lawful oaths, and generally do everything possible to vest title in said ASSIGNEE and to aid said ASSIGNEE, its successors, assigns and legal representatives to obtain and enforce proper protection for said invention in all countries.

Date: 12/03/2004

  
KUM-WENG LOO

Date: 12/03/2004

  
CHEK-LIM KHO